

Flex Circuits Capabilities			
No.	Item	Technical Data	
1	Layer Count	1~12 Layers	
2	Min. Line Width/Space	2/2 mil	
3	Max.Panel Size	500*1800mm(single side); 500*1200mm(double sides)	
4	Edge of Coverlay Opening to Trace	0.20mm(preferred)	
5	Min Space between coverlay and solder pad	0.15mm	
6	Polyimide Films	0.5 mil ,1 mil , 2 mils , 5mils	
7	Thermabond Adhesive	Thermosetting Adhesive, 3M high adhesion tape	
8	Copper Foils (RA or ED)	1/3oz, 1/2oz, 1oz, 2oz(special)	
9	Stiffeners	Polyimide, Rigid FR4, metal	
10	Solder Mask	Coverlay, LPI	
11	Min. Finished Hole size	0.2mm	
12	Max. Finished Hole size	6.30mm	
13	Hole tolerance	±0.05mm	
14	Min.space between holes	0.15mm	
15	Minimum conductor edge to outline edge	≥0.1mm	
16	Minimum space between coverlay and conductor	± 0.15mm	
17	Hole to outline edge	≥ 0.10mm	
18	Tooling tolerance	Knife(Soft) tooling	± 0.25mm
		Steel(Hard) tooling	± 0.05mm
		CNC drill/rout	± 0.10mm
19	Maximum Layer to Layer Mis-registration	± 0.10mm	
20	Copper Plated Thickness (PTH only)	8~15um;20~30um;30~70um(special)	
21	Surface Finish	Immersion Gold, Plating Hard Gold, OSP,ENEPIG	